

U.S. Patent Application Serial No. 10/087,913  
PRELIMINARY AMENDMENT  
TO RCE filed September 16, 2004

**AMENDMENTS TO THE SPECIFICATION:**

Page 4, please replace the paragraph starting in line 22 with the following amended paragraph:

In this invention, however, only a high-temperature process is disclosed as a specific process, where, for example, it is necessary to realize a temperature as high as the melting point  $[(221^{\circ}\text{C})]$  (about  $231^{\circ}\text{C}$ ) or above of tin in order to melt tin used as a coating metal, while it is also necessary to effect heat treatment at  $300$  to  $400^{\circ}\text{C}$  in order to cure the thermosetting resin. Accordingly, it is difficult therewith to avoid the problem of thermal damage to substrates, LSI's, and materials peripheral thereto.